AMENDMENTS TO THE CLAIMS

Claims 1-15 (Canceled)

16. (New) An optical device, comprising:

a laser diode generating heat;

a package including a bottom plate and a frame mounted on said bottom plate, said bottom plate and said frame being made of metal;

a wiring board mounted on said bottom plate and made of laminated ceramic;

a mount disposed on said bottom plate and made of metal, said mount mounting said laser diode thereon;

a driver circuit electrically connected to said wiring board for driving said laser diode, said driver circuit being mounted on said mount; and

a heat dissipating sheet directly in contact with said bottom plate to dissipate said heat generated by said laser diode,

heat generated by said driver circuit and said laser diode being conducted to outside of said package through said mount and said flexible heat dissipating sheet.

17. (New) The optical device according to claim 16,

wherein said heat dissipating sheet has a corrugated portion to secure a flexibility of said heat dissipating sheet.

18. (New) The optical device according to claim 17,

wherein said heat dissipating sheet is made of Cu or graphite.

19. (New) The optical device according to claim 16,

wherein said mount is made of CuW.

20. (New) The optical device according to claim 16,

further including an insulating plate disposed between said mount and said bottom plate.

21. (New) The optical device according to claim 20,

wherein said insulating plate extends from a lowermost portion of said laminated ceramic of said wiring board.

22. (New) The optical device according to claim 21,

wherein said heat dissipating sheet is directly in contact with said lowermost portion of said laminated ceramic.

23. (New) An optical device for emitting light, comprising:

a light-emitting element generating heat;

a box-shaped package including a metal bottom plate and a metal frame disposed on said metal bottom plate;

a thermo-electronic element disposed on said metal bottom plate for mounting said light-emitting element thereon; and

a heat dissipating sheet for dissipating said heat generated by said light-emitting element and said thermo-electric element;

a laminated ceramic part disposed on said metal bottom plate, said laminated ceramic part, surrounding said thereto-electronic element,

said heat dissipating sheet being directly in contact with an outer surface of said metal bottom plate.

24. (New) The optical device according to claim 23,

wherein said heat dissipating sheet is directly in contact with an outer surface of said metal frame.

25. (New) The optical device according to claim 23,

wherein said heat dissipating sheet has a corrugated portion to secure a flexibility of said heat dissipating sheet.

26. (New) The optical device according to claim 25,

wherein said heat dissipating sheet is made of Cu or graphite.

27. (New) An optical module for emitting and receiving optical signals, comprising:

a body including an optical receptacle and having an inner wall; and

an optical device installed in said body, said optical device including a laser diode for emitting said optical signal, a heat dissipating sheet, a package including a bottom plate, a frame and a sleeve disposed on said frame to be received in said optical receptacle,

wherein said heat dissipating sheet is directly in contact with said bottom plate of said optical device and said inner wall of said body to conduct heat generated by said laser diode.

28. (New) The optical module according to claim 27,

wherein said heat dissipating sheet has a corrugated portion to secure a flexibility of said heat dissipating sheet.

29. (New) The optical module according to claim 28,

wherein said sheet dissipating sheet is made of Cu or graphite.

30. (New) The optical module according to claim 27,

wherein said heat dissipating sheet has a folded configuration at a contact point to said inner wall of said body.

31. (New) The optical module according to claim 27,

wherein said optical device further provides a thermoelectric cooler for controlling a temperature of said laser diode, said thermoelectric cooler being disposed on said bottom plate to conduct heat generated by said thermoelectric cooler.

32. (New) The optical module according to claim 27,

wherein said optical device further provides a driver circuit for driving said laser diode and a mount for mounting said driver circuit and said laser diode, said mount being disposed on said bottom plate to conduct heat generated by said laser diode and said driver circuit.